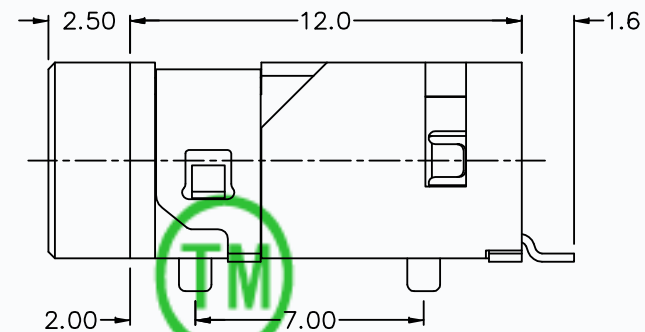
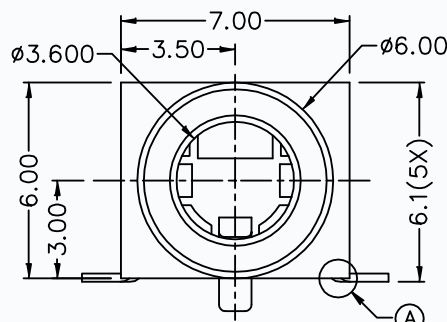
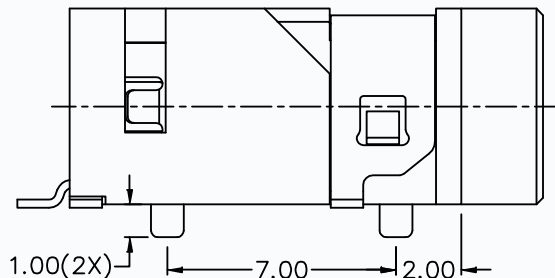
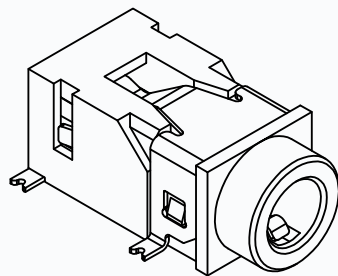
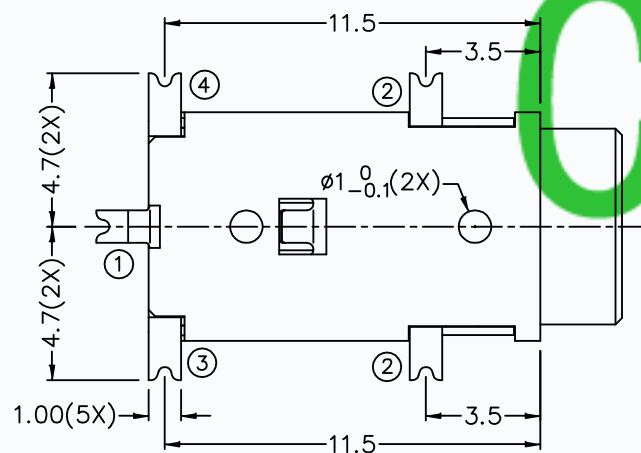


CAD FILE:



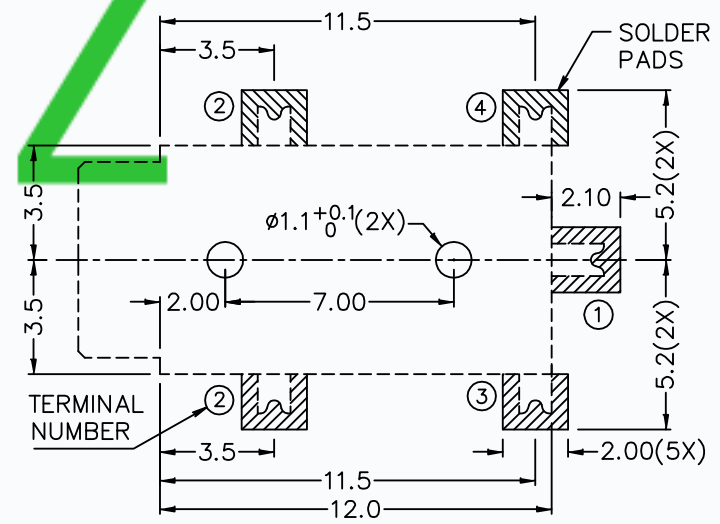
CMTDDZ



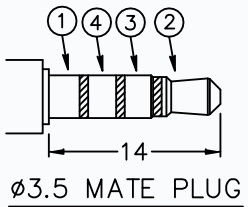
A DETAIL COPLANARITY

* MATERIAL

- TERMINAL 1 : COPPER ALLOY
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- TERMINAL 4 : COPPER ALLOY
- HOUSING : PA6T



RECOMMENDED SOLDER PAD LAYOUT (TOP VIEW)



φ3.5 MATE PLUG

MODEL NO.	T13-3511D
SCHMATIC	

APPD.	DESCRIPTIONS OF REVISION
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TOLERANCE UNLESS SPECIFIED
WITHIN 1.5mm : ±0.1mm
OVER 1.5mm : ±0.2mm

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TITLE : 3.5mm SMD PHONE JACK	UNIT : mm	DRWG NO.: CMTDDZ-T13-3511D-00		
MODEL: T13-3511D	SCALE: 3:1	DWN.	ERIC	2013-6-17
CMTDDZ 东莞市田都电子有限公司 DONGGUAN TIANDU ELECTRONICS CO.,LTD.		CHK'D	MAIKO	2013-6-17
		APPD.	Coco	2013-6-17